CareerCross by JAC Recruitment

cādence®

プリント基板(PCB)&半導体パッケージ設計担当アプリケーション・エンジニア

募集職種

採用企業名
日本ケイデンス・デザイン・システムズ社

求人ID
1501208

業種
電気・電子・半導体

雇用形態
正社員

勤務地
神奈川県, 横浜市港北区

給与
経験考慮の上、応相談

更新日
2025年01月28日 01:00

応募必要条件

職務経験
6年以上

キャリアレベル
中途経験者レベル

英語レベル
流暢

日本語レベル
ネイティブ

最終学歴
大学卒：学士号

現在のビザ
日本での就労許可が必要です

募集要項

Business Content

- Customer support, consulting and project management for Cadence printed circuit board and semiconductor package design tools
    - Identify customer issues and propose and provide methodologies using Cadence products
    - Understand customer technical challenges and use them to improve products
    - Providing custom scripts to suit your design environment
    - Product feature demonstrations, presentations and training instructors

Main products: Allegro PCB Designer, Allegro Package Designer Plus (APD Plus), Integrity 3DIC, Innovus, etc.

https://www.cadence.com/en_US/home/solutions/3dic-design-solutions.html

Eligibility

- Those who have majored in electrical and electronic engineering, or have equivalent experience and knowledge, and are eager to take on new challenges.

スキル・資格

Experience/Skills

- More than 5 years of knowledge and experience in layout design verification of printed circuit boards or IC packages, or more than 5 years of experience supporting layout design verification tools as a CAD specialist
- Programming experience: SKILL, Perl, Tcl, Python etc. preferred
- Knowledge of 2.5D/3D-IC design is preferred
- Ability to communicate with members and customers from various fields
- Experience in managing projects with clients
- Ability to communicate by email in English and have technical conversations in English
- Ability to communicate in Japanese (N1 level, 3 years or more of business experience in Japan using Japanese)

会社説明

スキル・資格

Experience/Skills